

关键参数
Key Parameters

V_{DSmax}		1400	V
$R_{DS(on)}$	Typ.	13.6	mΩ
I_D	Max.	147	A
Die Size		6.00*5.00	mm ²

特点
Features

- 高开关频率 High Switching Frequency
- 低开关损耗 Low Switching Loss
- 软、快速开关 Soft, fast Switching
- 易并联使用 Easy Paralleling

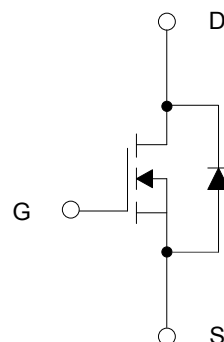
电路结构
Circuit Configuration


图 1. 电路结构

Fig. 1 Circuit configuration

最大额定值
Maximum Ratings

符号 Symbol	参数名称 Parameter	数值 Value	单位 Unit
V_{DSmax}	漏源极电压 Drain-source voltage	1400	V
V_{GSmax}	栅源电压 Gate-source voltage	-8/+23	V
V_{GSop}	栅源电压 Gate-source voltage	-4/+18	V
I_D	持续正向电流, 由 $T_{vj\ max}$ 限制 Continuous forward current, limited by $T_{vj\ max}$	147	A
I_{DM}	最大重复正向电流, 由 $T_{vj\ max}$ 限制 Maximum repetitive forward current, limited by $T_{vj\ max}$	294	A
$T_{vj\ max}$	最大允许结温 Max. Junction temperature	175	°C
$T_{vj(op)}$	工作结温 Operation junction temperature	-40...+175	°C
$T_{Proc}^{(*)}$	最大加工温度 Maximum processing temperature	400	°C

注意: 该器件对静电敏感, 用户须采取 ESD 防护措施。

Caution: This device is sensitive to electrostatic discharge. Users should follow ESD handling procedures.

电特性值
Electrical Characteristics

除非特别声明，否则 $T_{vj} = 25\text{ }^{\circ}\text{C}$
 $T_{vj} = 25\text{ }^{\circ}\text{C}$ unless otherwise stated

符号 Symbol	参数名称 Parameter	测试条件 Test Conditions	最小值 Min.	典型值 Typ.	最大值 Max.	单位 Unit
I_{DSS}	零栅压漏极电流 Zero gate voltage drain current	$V_{GS} = 0V, V_{DS} = V_{DSmax}$			20	μA
		$V_{GS} = 0V, V_{DS} = V_{DSmax}, T_{vj} = 175\text{ }^{\circ}\text{C}$			20	μA
I_{GSS}	栅极漏电流 Gate leakage current	$V_{GS} = V_{GSmax}, V_{DS} = 0V$			250	nA
$V_{GS(th)}^{(*2)}$	栅极-源极阈值电压 Gate threshold voltage	$I_D = 25\text{ mA}, V_{GS} = V_{DS}$	2.4	3.0	3.6	V
		$I_D = 25\text{ mA}, V_{GS} = V_{DS}, T_{vj} = 175\text{ }^{\circ}\text{C}$	1.8	2.4	3.0	V
$R_{DS(ON)}$	漏极-源极通态电阻 Drain-source on-state resistance	$V_{GS} = 18V, I_D = 73.5A$		13.6		m Ω
		$V_{GS} = 18V, I_D = 73.5A, T_{vj} = 175\text{ }^{\circ}\text{C}$		29.0		m Ω
g_{fs}	跨导 Forward transconductance	$V_{DS} = 20V, I_D = 73.5A$		165		S
C_{iss}	输入电容 Input capacitance	$V_{DS} = 1000V, V_{GS} = 0V,$ $f = 100\text{ kHz}, V_{AC} = 25\text{ mV}$		7425		pF
C_{oss}	输出电容 Output capacitance			219		pF
C_{rss}	反向传输电容 Reverse transfer capacitance			14		pF
E_{oss}	电容存储能量 C_{oss} Stored Energy			105		μJ
R_{Gint}	内部栅极电阻 Internal gate resistor	$V_{GS} = 0V$		7.2		Ω
Q_{gs}	栅源电荷 Gate to source charge	$V_{DS} = 1000V, I_D = 135A,$ $V_{GS} = -4V/+18V$		81		nC
Q_{gd}	栅漏电荷 Gate to drain charge			173		nC
Q_g	总栅极电荷 Total gate charge			254		nC
V_{SD}	二极管正向电压 Diode forward voltage	$I_{SD} = 73.5A, V_{GS} = -4V$		4.6		V
		$I_{SD} = 73.5A, V_{GS} = -4V, T_{vj} = 175\text{ }^{\circ}\text{C}$		4.2		V

注意: 1.(*)1 表示最长持续时间 10min((*)1) indicates 10min, maximum);

Note: 2.(*)2 表示做过预处理后的测试值((*)2 indicates $V_{GS(th)}$ is preprocessed);

电特性值

Electrical Characteristics

符号 Symbol	参数名称 Parameter	测试条件 Test Conditions		最小值 Min.	典型值 Typ.	最大值 Max.	单位 Unit
$t_{d(off)}$	关断延迟时间 Turn-off delay time	$I_D = 140A$, $V_{DS} = 1100V$, $V_{GS} = -4/+18V$, $R_{G(OFF)} = 1.6\Omega$, $dv/dt = 39233V/\mu s$ ($T_{vj} = 175\text{ }^{\circ}C$)	$T_{vj} = 25\text{ }^{\circ}C$		59		ns
			$T_{vj} = 175\text{ }^{\circ}C$		82		
t_f	下降时间 Fall time		$T_{vj} = 25\text{ }^{\circ}C$		36		ns
			$T_{vj} = 175\text{ }^{\circ}C$		34		
E_{OFF}	关断损耗 Turn-off energy loss		$T_{vj} = 25\text{ }^{\circ}C$		225		μJ
			$T_{vj} = 175\text{ }^{\circ}C$		233		
$t_{d(on)}$	开通延迟时间 Turn-on delay time	$I_D = 140A$, $V_{DS} = 1100V$, $V_{GS} = -4/+18V$, $R_{G(ON)} = 1.8\Omega$, $di/dt = 3442A/\mu s$ ($T_{vj} = 175\text{ }^{\circ}C$)	$T_{vj} = 25\text{ }^{\circ}C$		44		ns
			$T_{vj} = 175\text{ }^{\circ}C$		46		
t_r	上升时间 Rise time		$T_{vj} = 25\text{ }^{\circ}C$		45		ns
			$T_{vj} = 175\text{ }^{\circ}C$		38		
E_{ON}	开通损耗 Turn-on energy loss		$T_{vj} = 25\text{ }^{\circ}C$		742		μJ
			$T_{vj} = 175\text{ }^{\circ}C$		892		
Q_{rr}	二极管反向恢复电荷 Diode reverse recovery charge	$I_D = 140A$, $V_{DS} = 1100V$, $-di_{SD}/dt = 3442A/\mu s$ ($T_{vj} = 175\text{ }^{\circ}C$)	$T_{vj} = 25\text{ }^{\circ}C$		1000		nC
			$T_{vj} = 175\text{ }^{\circ}C$		1000		
I_{rr}	二极管反向恢复电流 Diode reverse recovery current		$T_{vj} = 25\text{ }^{\circ}C$		28		A
			$T_{vj} = 175\text{ }^{\circ}C$		56		

1.(*1) dv/dt : 定义为关断波形电压 V_{DS} 上升段, 40% V_{CE} 至 60% V_{DS} 区间段的斜率(*1) dv/dt : Defined as the slope of waveform of 40% V_{DS} to 60% V_{DS} during turn off)

注意:

Note:

2.(*2) di/dt : 定义为开通波形电流 I_D 上升段, 40% I_D 至 60% I_D 区间段的斜率(*2) di/dt : Defined as the slope of waveform of 40% I_D to 60% I_D during turn on)

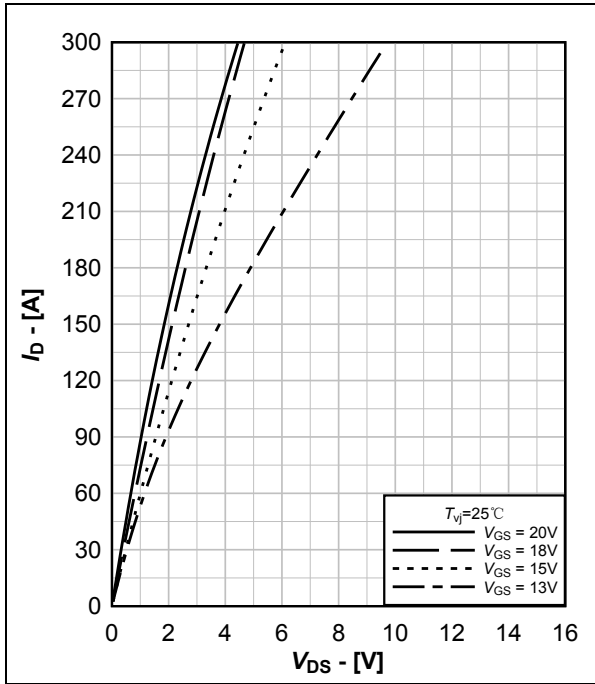


图 2. 输出特性典型曲线, $I_D = f(V_{DS})$, $T_{vj} = 25\text{ }^{\circ}\text{C}$

Fig.2 Typical output characteristics, $I_D = f(V_{DS})$, $T_{vj} = 25\text{ }^{\circ}\text{C}$

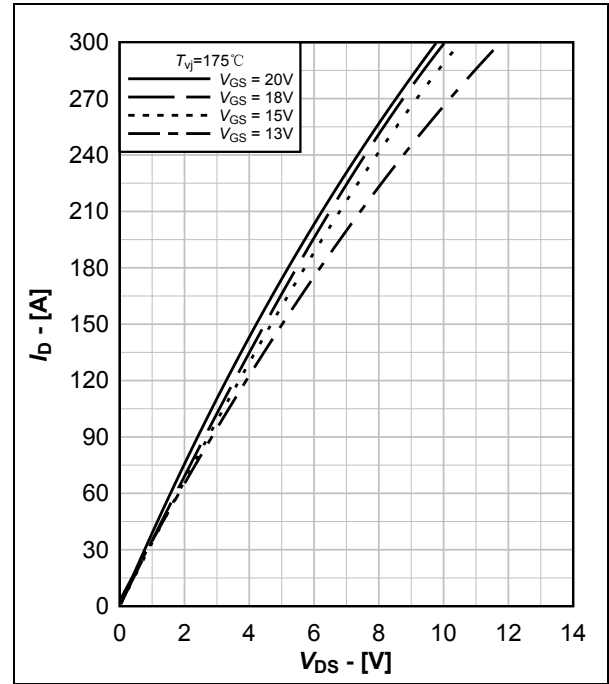


图 3. 输出特性典型曲线, $I_D = f(V_{DS})$, $T_{vj} = 175\text{ }^{\circ}\text{C}$

Fig.3 Typical output characteristics, $I_D = f(V_{DS})$, $T_{vj} = 175\text{ }^{\circ}\text{C}$

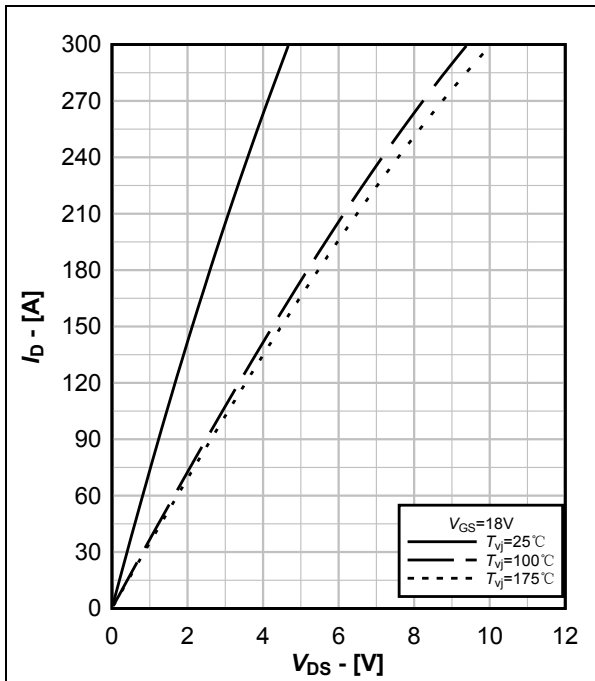


图 4. 输出特性典型曲线, $I_D = f(V_{DS})$

Fig.4 Typical output characteristics, $I_D = f(V_{DS})$

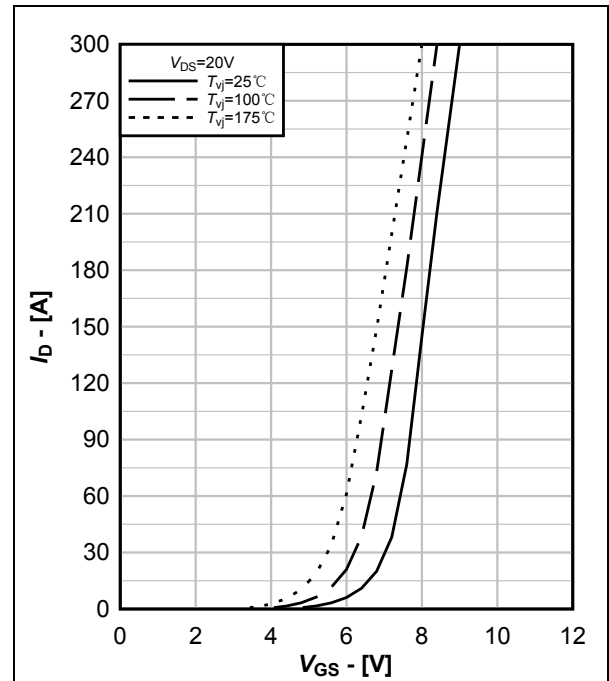


图 5. 传输特性典型曲线, $I_D = f(V_{GS})$

Fig.5 Typical transfer characteristics, $I_D = f(V_{GS})$

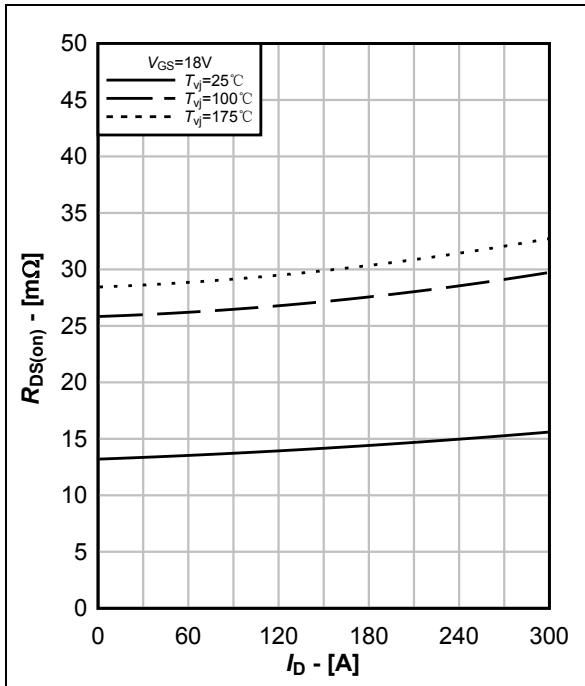

图 6. 导通电阻典型曲线, $R_{DS(on)} = f(I_D)$

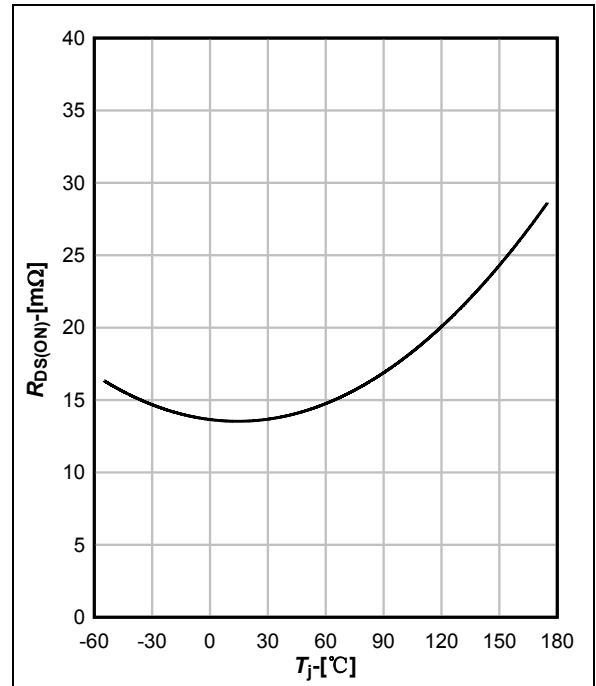
Fig.6 Typical On-Resistance characteristics, $R_{DS(on)} = f(I_D)$

图 7. 导通电阻典型曲线, $R_{DS(on)} = f(T_J)$

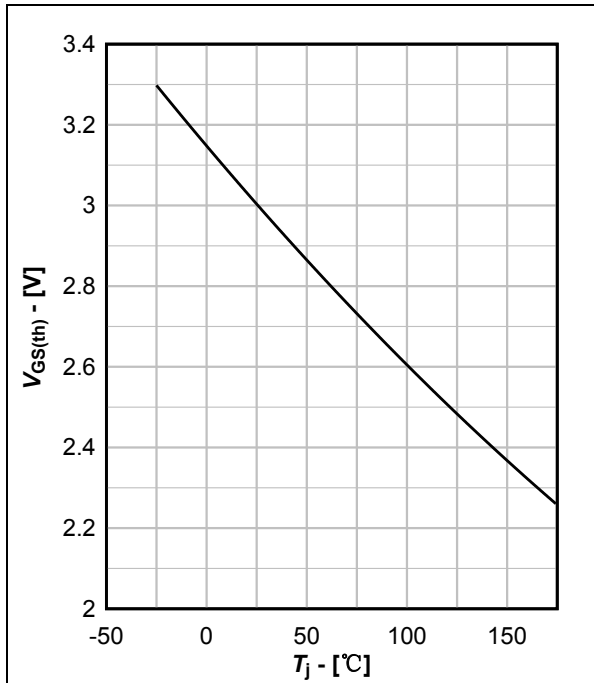
Fig.7 Typical On-Resistance characteristics, $R_{DS(on)} = f(T_J)$

图 8. 阈值电压典型曲线, $V_{GS(th)} = f(T_J)$

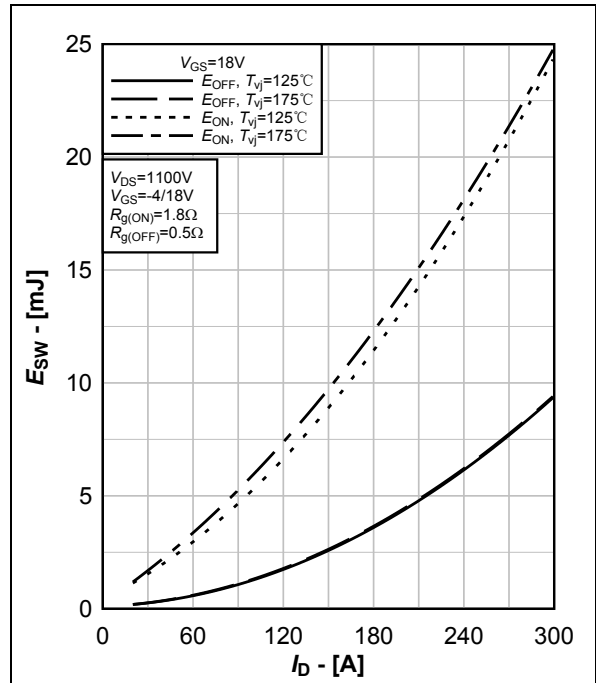
Fig.8 Typical $V_{GS(th)}$ characteristics, $V_{GS(th)} = f(T_J)$

图 9. MOSFET 开关损耗典型曲线, $E_{off} = f(I_D)$, $E_{on} = f(I_D)$

Fig.9 Typical MOSFET switching energy, $E_{off} = f(I_D)$, $E_{on} = f(I_D)$

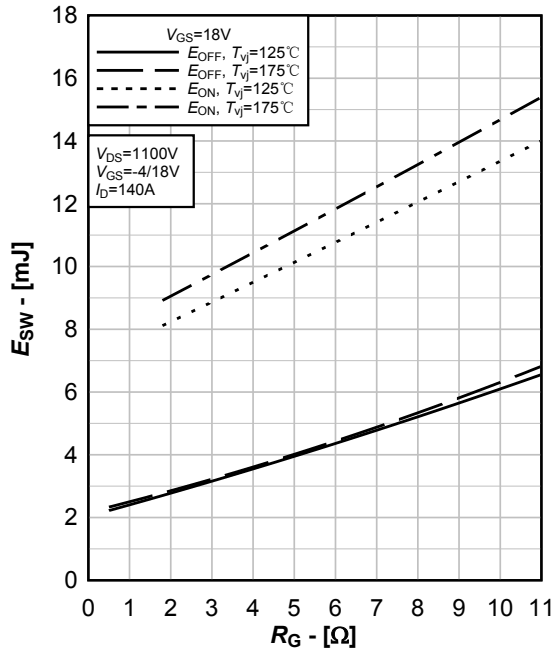


图 10. MOSFET 开关损耗典型曲线, $E_{on}=f(R_G)$, $E_{off}=f(R_G)$

Fig.10 Typical MOSFET switching energy, $E_{on}=f(R_G)$, $E_{off}=f(R_G)$

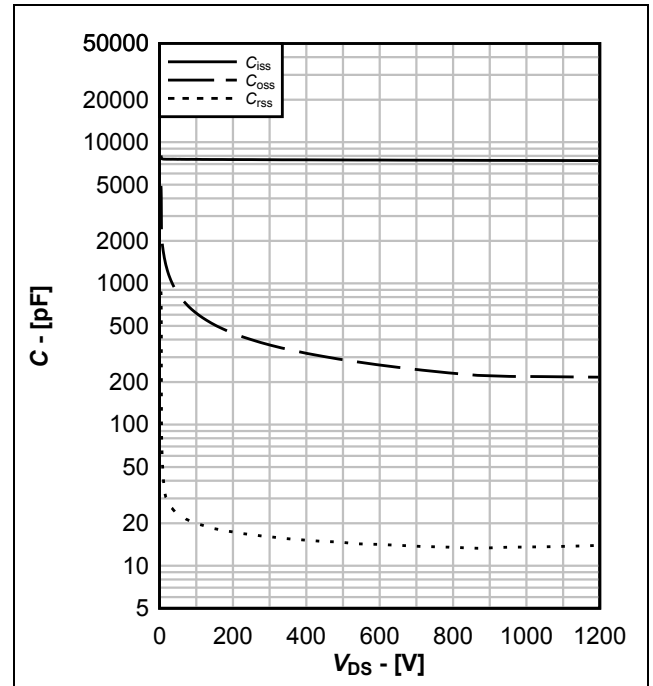


图 11. 电容特性典型曲线, $C=f(V_{DS})$

Fig.11 Typical capacity characteristic, $C=f(V_{DS})$

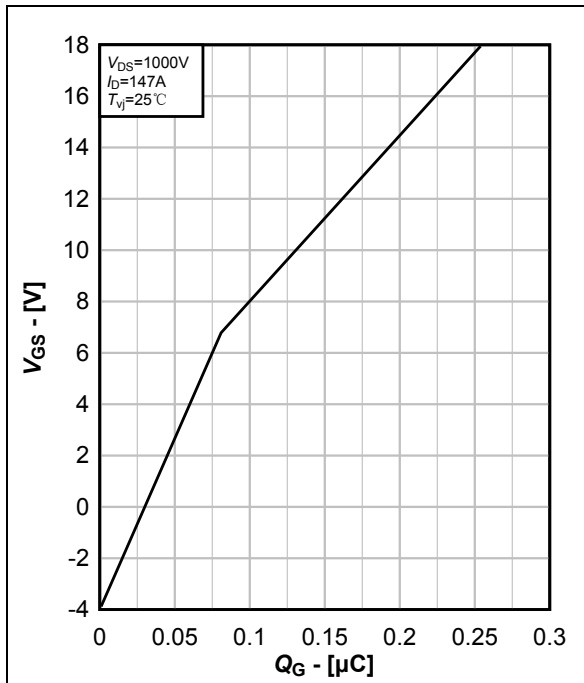


图 12. 栅极电荷特性典型曲线, $V_{GS}=f(Q_G)$

Fig.12 Typical gate charge characteristic, $V_{GS}=f(Q_G)$

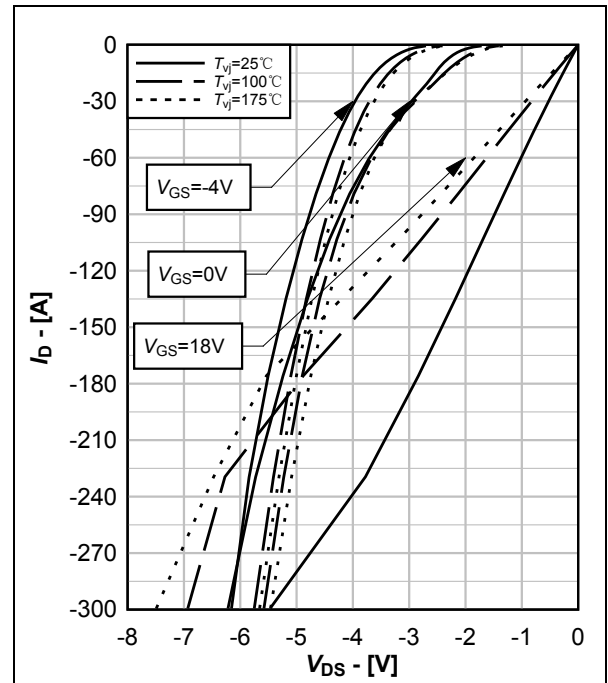


图 13. 体二极管及第三象限输出特性典型曲线, $I_D=f(V_{DS})$

Fig.13 Typical body diode output and 3rd quadrant characteristic, $I_D=f(V_{DS})$

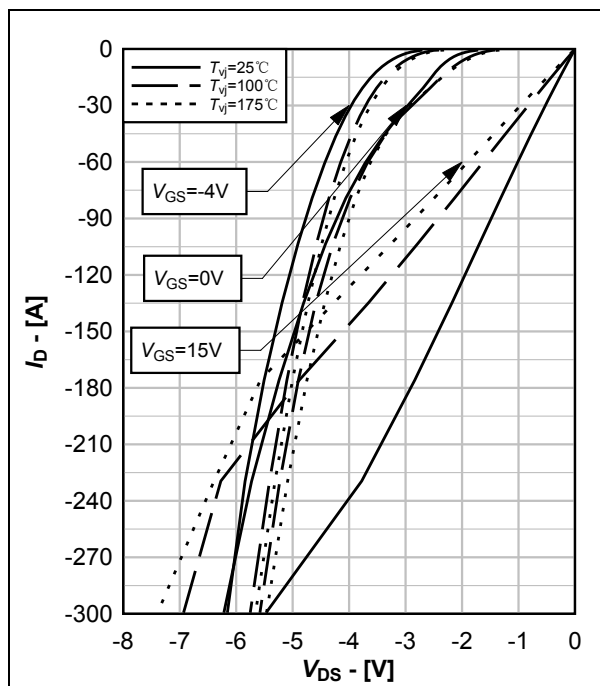
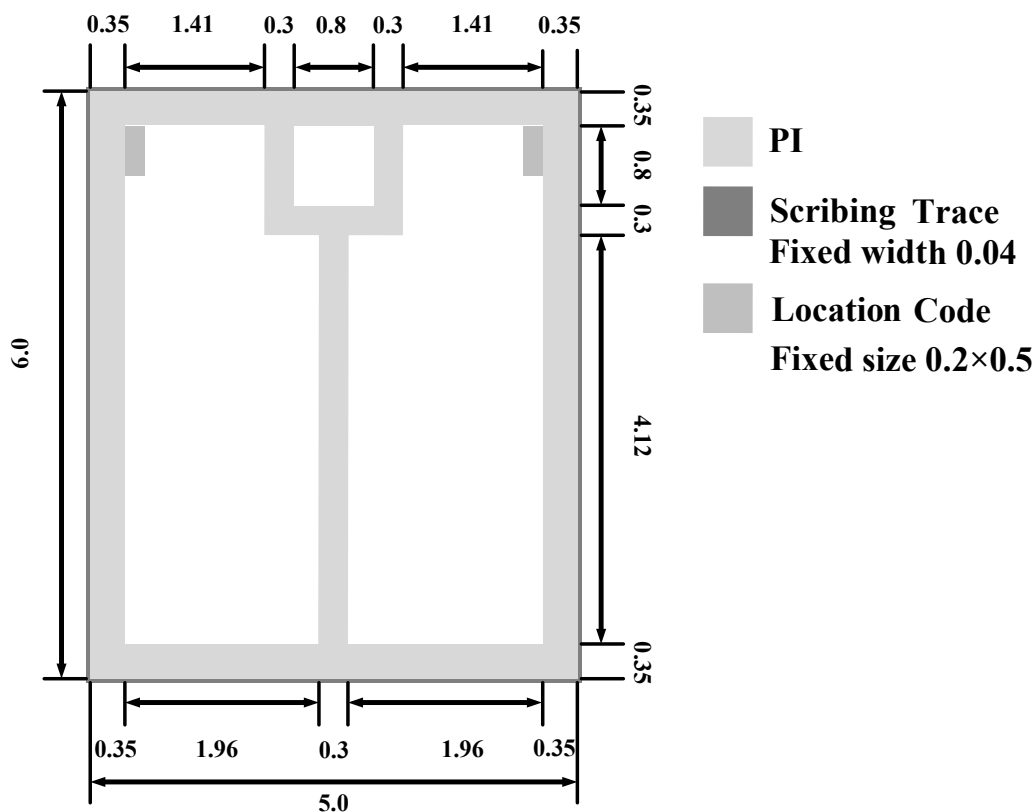


图 14. 体二极管及第三象限输出特性典型曲线, $I_D = f(V_{DS})$

Fig.14 Typical body diode output and 3rd quadrant
characteristic, $I_D = f(V_{DS})$

工艺参数值
Mechanical Parameters

芯片尺寸 Chip size	6.00*5.00	mm ²
源极键合区尺寸(不包含开尔文源级) Source pad size (excl. Kelvin Source pad)	见芯片尺寸图 See chip drawing	mm ²
栅极键合区尺寸 Gate pad size	0.60*0.50	mm ²
总面积 Area total	30.00	mm ²
厚度 Thickness	120±10	μm
晶圆尺寸 Wafer size	150	mm
每片晶圆上最大芯片数 Max. possible chips per wafer	462	
正面金属 Frontside (Source and Gate) metal	AlSi: 5.0μm	
背面金属 Backside (Drain) metal	Ti:Ni:Ag (0.05:0.75:0.25μm)	
正面钝化 Passivation frontside	Polyimide	
建议存储环境 Recommended storage environment	存储在原始容器中, 23°C 干燥氮气柜小于 6 个月 Store in original container, in dry nitrogen, <6 months at an ambient temperature of 23°C	



单位：毫米

Unit:mm

图 2. 芯片外观尺寸

Fig. 2 Chip drawing

株洲中车时代半导体有限公司

ZHUZHOU CRRC TIMES SEMICONDUCTOR CO., LTD

地 址	Address	湖南省株洲市石峰区田心工业园	Tianxin Industrial Park, Shifeng District, ZhuZhou City, Hunan Province, China
邮 编	Zipcode	412001	
电 话	Telephone	+86 (0)731-28498268, 28498238, 28493472	
传 真	Fax	+86 (0)731-28498851, 28498494	
电子邮箱	Email	ctsc@csrzc.com	
网 址	Web Site	http:// ctsc.csrzc.com	

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